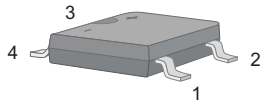
1.5A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

FEATURES:

- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000 V
- Forward Current - 1.5 A
- High Surge Current Capability
- Designed for Surface Mount Application

PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



ABF Package

MECHANICAL DATA

- Case: ABF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 82mg 0.0029oz

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.
Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	TB1F-15	TB2F-15	TB4F-15	TB6F-15	TB8F-15	TB10F-15	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at T_c = 125 °C	I_O	1.5						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	50 (Typical : 55A)						A
Maximum Forward Voltage at 1.5 A	V_F	1.1						V
Maximum DC Reverse Current at Rated DC Blocking Voltage @T_A=25 °C @T_A=125 °C	I_R	5 100						μA
Typical Junction Capacitance (Note1)	C_j	25						pF
Typical Thermal Resistance (Note2)	$R_{\theta JA}$ $R_{\theta JC}$	65 16						°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150						°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

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Fig.1 Average Rectified Output Current Derating Curve

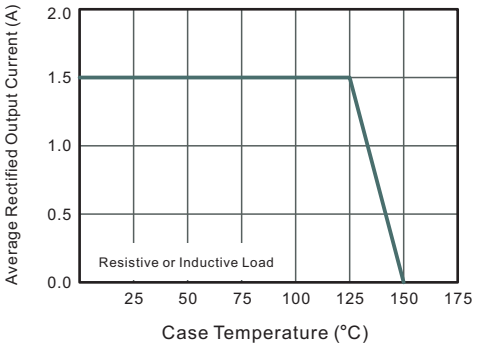


Fig.2 Typical Reverse Characteristics

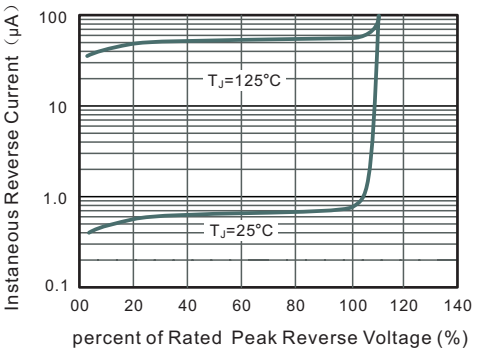


Fig.3 Typical Instaneous Forward Characteristics

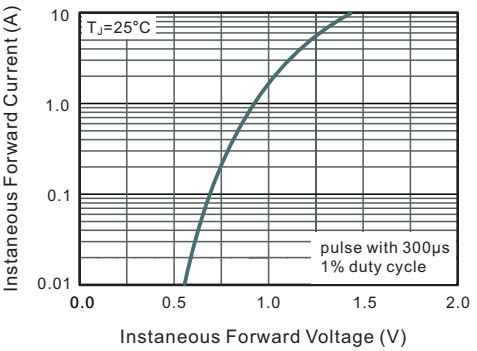


Fig.4 Typical Junction Capacitance

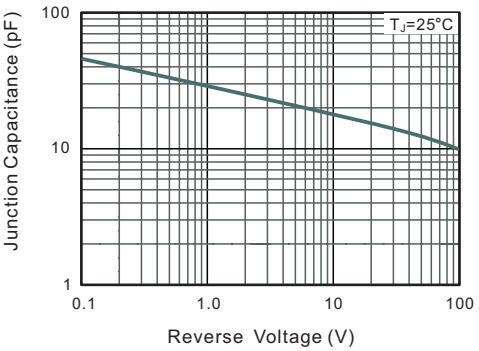
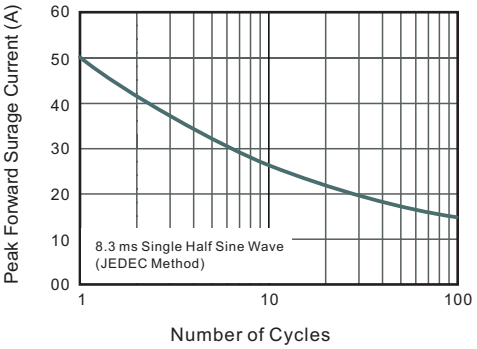


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current



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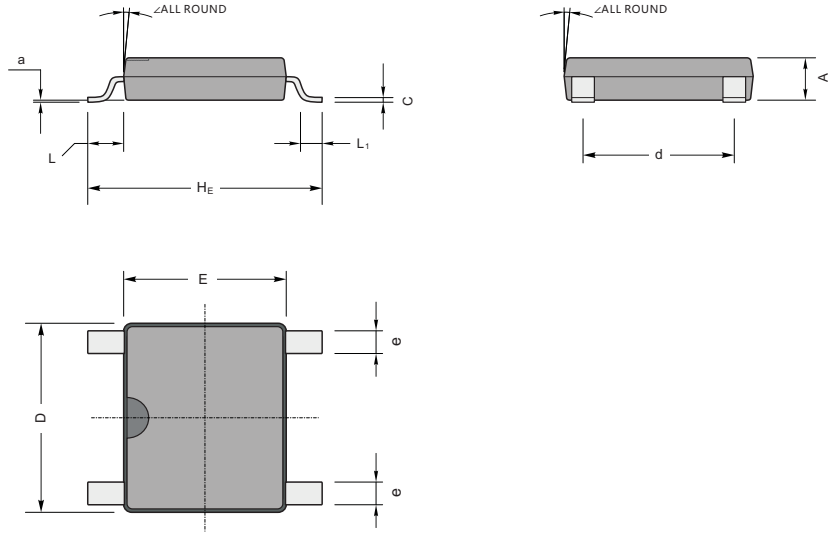
PACKAGE OUTLINE

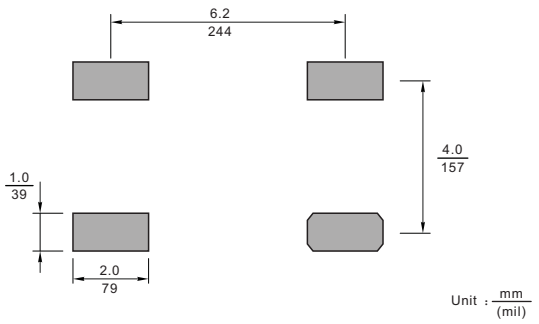
Plastic surface mounted package; 4 leads ABF



ABF mechanical data

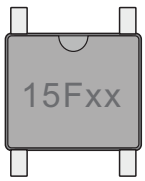
UNIT		A	C	D	E	H_E	d	e	L	L_1	a	∠
mm	max	1.2	0.22	5.2	4.5	6.4	4.2	0.7	0.95	0.6	0.2	7°
	min	1.0	0.15	4.9	4.2	6.0	3.8	0.5				
mil	max	47	8.7	205	177	252	165	28	37	24	8	
	min	39	5.9	193	166	236	150	20				

The recommended mounting pad size



Marking

Type number	Marking code
TB1F-15	15F1
TB2F-15	15F2
TB4F-15	15F4
TB6F-15	15F6
TB8F-15	15F8
TB10F-15	15F10



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